

## PMP10604 REV 2 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP10604	Any	Printed Circuit Board	
C1, C2, C7, C12, C13	5	0.1uF	GRM188R71H104KA93D	MuRata	CAP, CERM, 0.1 $\mu$ F, 50 V, +/- 10%, X7R, 0603	0603
C3, C4	2	22uF	GRM32ER71C226KE18L	MuRata	CAP, CERM, 22 $\mu$ F, 16 V, +/- 10%, X7R, 1210	1210
C5	1	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47 $\mu$ F, 25 V, +/- 10%, X7R, 0603	0603
C6	1	22uF	EEE-FK1H220P	Panasonic	CAP, AL, 22 $\mu$ F, 50 V, +/- 20%, 0.88 ohm, SMD	SMT Radial D
C8, C11	2	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1 $\mu$ F, 50 V, +/- 10%, X7R, 0805	0805
C9, C10, C14	3	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 $\mu$ F, 50 V, +/- 10%, X7R, 1210	1210
C15	1	2.2uF	GRM188R71A225KE15D	MuRata	CAP, CERM, 2.2 $\mu$ F, 10 V, +/- 10%, X7R, 0603	0603
FB1	1	600 ohm	FBMH3225HM601NT	Taiyo Yuden	Ferrite Bead, 600 ohm @ 100 MHz, 3 A, 1210 (H=2.5mm)	1210 (H=2.5mm)
FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
GND, IN+, IN-, Vo	4	Double	1502-2	Keystone	Terminal, Turret, TH, Double	Keystone1502-2
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
L1	1		CLF7045T-3R3N-D	TDK Corporation	FIXED IND 3.3UH 4.1A 16.4 MOHM, AUTOMOTIVE	Nonstandard, 7.20mm x 6.90mm
LCF1	1	11uH	744273102	Würth Elektronik eiSos	Coupled inductor, 11 $\mu$ H, 2.5 A, 0.03 ohm, SMD	SMD, 4-Leads, Body 9.5x8.3mm
LF1	1	2.2uH	74408943022	Würth Elektronik eiSos	Inductor, Shielded Drum Core, Ferrite, 2.2uH, 3A, 0.026 ohm, SMD	4.8x3.8x4.8mm
U1	1		LM53603PWP	Texas Instruments	6th GENERATION BUCK REGULATOR, PWP0016H	PWP0016H

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